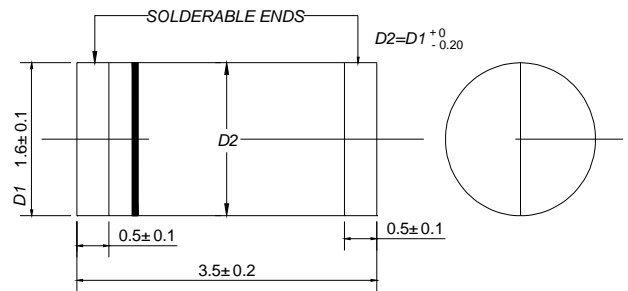




## Features

- ◇ Plastic package has underwriters laboratory flammability classifications
- ◇ For surface mounted applications
- ◇ Low profile package
- ◇ Built-in strain relief, ideal for automated placement
- ◇ Glass passivated chip junction
- ◇ High temperature soldering: 250°C/10 seconds at terminals

## DO - 213AA



Dimensions in millimeters

## Mechanical Data

- ◇ Case: JEDEC DO-213AA, molded plastic over passivated chip
- ◇ Polarity: Color band denotes cathode end
- ◇ Weight: 0.0014 ounces, 0.036 gram

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

		GL34A	GL34B	GL34D	GL34G	GL34J	GL34K	GL34M	UNITS
Polarity color bands (2nd Band)		Gray	Red	Orange	Yellow	Green	Blue	Violet	
Maximum recurrent peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RWS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current @ $T_A=75^\circ\text{C}$	$I_{F(AV)}$	0.5							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	10.0							A
Maximum instantaneous forward voltage at 0.5 A	$V_F$	1.2				1.3			V
Maximum DC reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=125^\circ\text{C}$	$I_R$	5.0				50.0			$\mu\text{A}$
Typical junction capacitance (NOTE 2)	$C_J$	4.0							pF
Typical reverse recovery time (NOTE 3)	$t_{rr}$	1.5							$\mu\text{s}$
Typical thermal resistance (NOTE 4)	$R_{\theta JA}$	150							$^\circ\text{C/W}$
operating junction temperature range	$T_J$	-55-----+150							$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55-----+150							$^\circ\text{C}$

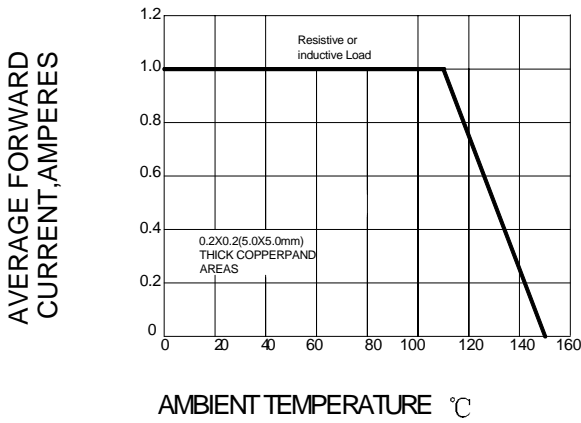
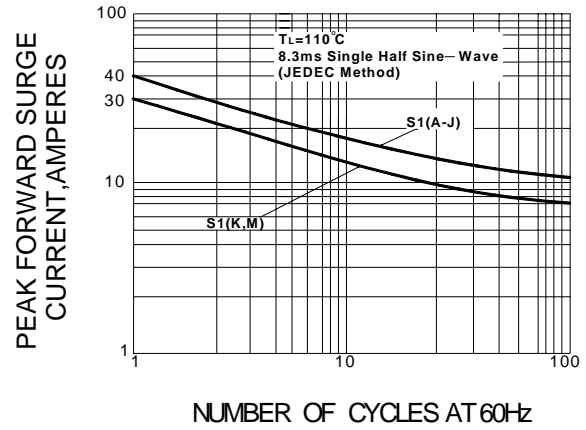
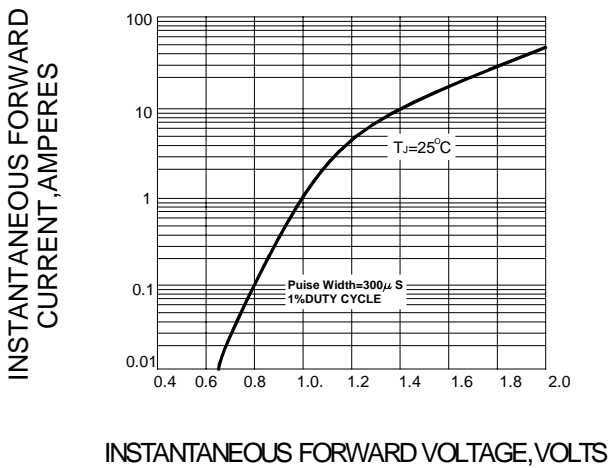
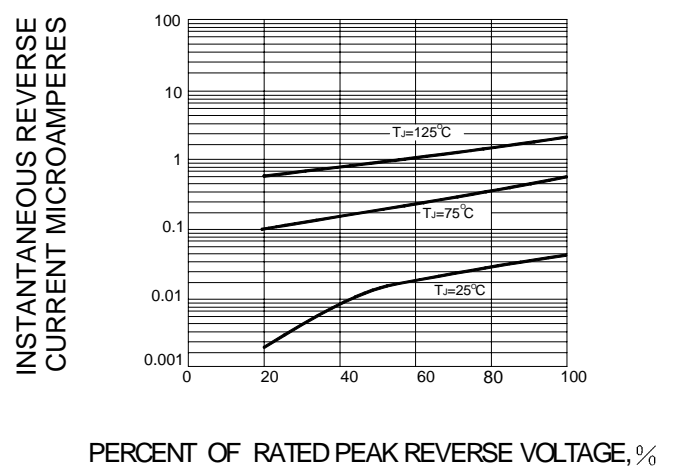
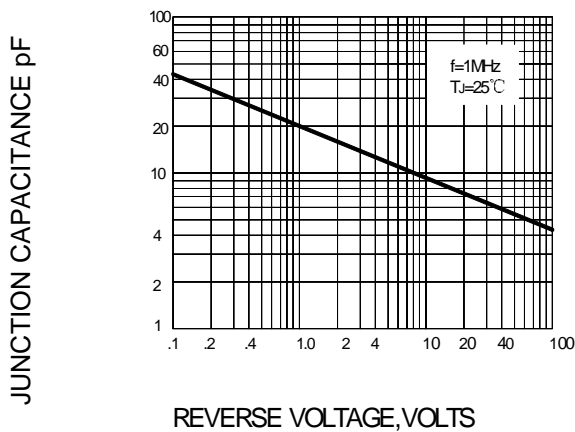
NOTE: 1. Measured at 1.0MHz and applied reverse voltage of 4.0volts

2. Thermal resistance from junction to ambient and junction to lead P.C.B mounted on 0.27"X0.27"(7.0X7.0mm<sup>2</sup>) copper pad areas

3. Measured with  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{rr}=0.25\text{A}$ .

4. Thermal resistance from junction to ambient and junction to lead P.C.B. mounted on 0.27"X0.27"(7.0X7.0mm<sup>2</sup>) copper pad areas

## Ratings AND Characteristic Curves

**FIG.1 – FORWARD DERATING CURVE**

**FIG.2 PEAK FORWARD SURGE CURRENT**

**FIG.3 – TYPICAL FORWARD CHARACTERISTICS**

**FIG.4 – TYPICAL REVERSE CHARACTERISTICS**

**FIG.5-TYPICAL JUNCTION CAPACITANCE**

**FIG.6-TRANSIENT THERMAL IMPEDANCE**
